Tool ID: 1812
Tool Location: P154

Equipment Information Sheet

Finetech Fineplacer pico ma Manual Die Bonder

Manager: Giovanni Sartorello 607-254-4853
Backup: Ben Infante 607-254-4813

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY
USAGE RESTRICTIONS

Chip Bonding tool changes may only be done after training by CNF staff.

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 30 minutes

- Components assembled in this system must be very clean!
- Contamination (Organics) can cause bonding to the heaters and heater damage.
- Very hot surfaces are used in this system! Don't touch them!

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

Last Updated: 08/21/2026